**Section 307.4300 General Provisions**

a) Applicability. Except as provided in subsection (a)(3) or (a)(4), this Subpart BH applies to discharges resulting from plants that perform on any basis material any of the six metal finishing operations listed in subsection (a)(1). If any of those six operations are present, then this Subpart BH applies also to discharges from the forty process operations specified in subsection (a)(2).

1) Six metal finishing operations. Electroplating, electroless plating, anodizing, coating (chromating, phosphating, and coloring), chemical etching and milling, and printed circuit board manufacture.

2) Forty additional process operations. Cleaning, machining, grinding, polishing, tumbling, burnishing, impact deformation, pressure deformation, shearing, heat treating, thermal cutting, welding, brazing, soldering, flame spraying, sandblasting, other abrasive jet machining, electric discharge machining, electrochemical machining, electron beam machining, laser beam machining, plasma arc machining, ultrasonic machining, sintering, laminating, hot-dip coating, sputtering, vapor plating, thermal infusion, salt bath descaling, solvent degreasing, paint stripping, painting, electrostatic painting, electropainting, vacuum metalizing, assembly, calibration, testing, and mechanical plating.

3) Exclusions. This Subpart BH does not apply if there are pretreatment standards that are effective and applicable for the following industrial categories:

A) Nonferrous metal smelting and refining (Subpart V);

B) Coil coating (Subpart CN);

C) Porcelain enameling (Subpart CO);

D) Battery manufacturing (Subpart CJ);

E) Iron and steel (Subpart U);

F) Metal casting foundries (Subpart CM);

G) Aluminum forming (Subpart CP);

H) Copper forming (Subpart CQ);

I) Plastic molding and forming (Subpart CL);

J) Nonferrous forming (Subpart CT); and

K) Electrical and electronic components (Subpart CR.

4) This Subpart BH does not apply to the following:

A) Metallic platemaking and gravure cylinder preparation conducted within or for printing and publishing facilities; and

B) Existing indirect discharging job shops and independent printed circuit board manufacturers that are covered by Subpart N.

b) General Definitions. The Board incorporates by reference 40 CFR 433.11 (2003). This incorporation includes no later amendments or editions.

c) Monitoring Requirements. The Board incorporates by reference 40 CFR 433.12 (2003). This incorporation includes no later amendments or editions.

(Source: Amended at 47 Ill. Reg. 4662, effective March 23, 2023)